

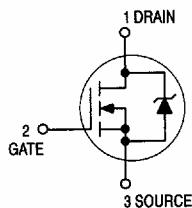
**TMOS Field Effect Transistor
Dual In-Line Package
N-Channel Enhancement Mode**

- Ideal for Peripheral Control Applications
- Intermediate 1 Watt Power Capability
- Standard DIP Outline



**IRFD210
IRFD213**

**TMOS FET
TRANSISTORS
FET DIP**



CASE 370-01, STYLE 1

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	IRFD210	IRFD213	Unit
Drain-Source Voltage	V_{DSS}	200	150	Vdc
Drain-Gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	V_{DGR}	200	150	Vdc
Gate-Source Voltage	V_{GS}	± 20		Vdc
Drain Current — Continuous $T_C = 25^\circ\text{C}$ — Pulsed	I_D I_{DM}	0.6 2.5	0.45 1.8	Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	1.0 0.008		Watts mW/ $^\circ\text{C}$
Operating and Storage Temperature Range	T_J, T_{stg}	−55 to +150		$^\circ\text{C}$

THERMAL CHARACTERISTICS

Thermal Resistance — Junction-to-Ambient	$R_{\theta JA}$	120	$^\circ\text{C/W}$
--	-----------------	-----	--------------------

IRFD210 IRFD213
ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain-Source Breakdown Voltage ($V_{GS} = 0$, $I_D = 250 \mu\text{A}$)	IRFD210 IRFD213	$V_{(BR)DSS}$	200 150	—	—
Zero Gate Voltage Drain Current ($V_{DSS} = \text{Rated } V_{DSS}$, $V_{GS} = 0 \text{ V}$)	I_{DSS}	—	—	250	μA
Gate-Body Leakage Current, Forward ($V_{GSF} = 20 \text{ V}$)	I_{GSSF}	—	—	500	nAdc
Gate-Body Leakage Current, Reverse ($V_{GSR} = -20 \text{ V}$)	I_{GSSR}	—	—	-500	nAdc
ON CHARACTERISTICS					
Gate Threshold Voltage ($I_D = 250 \mu\text{A}$, $V_{DS} = V_{GS}$)	$V_{GS(\text{th})}$	2.0	—	4.0	Vdc
Static Drain-Source On-Resistance (1) ($V_{GS} = 10 \text{ Vdc}$, $I_D = 0.3 \text{ A}$)	IRFD210 IRFD213	$R_{DS(\text{on})}$	—	—	1.5 2.4
On-State Drain Current (1) ($V_{GS} = 10 \text{ V}$, $V_{DS} = 5.0 \text{ V}$)	IRFD210, IRFD211 IRFD212, IRFD213	$I_{D(\text{on})}$	1.5 2.4	—	—
Forward Transconductance (1) ($I_D = 0.3 \text{ A}$, $V_{DS} = 5.0 \text{ V}$)	g_{FS}	0.5	—	—	mhos
CAPACITANCE					
Input Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0,$ $f = 1.0 \text{ MHz})$	C_{ISS}	—	—	150
Output Capacitance		C_{OSS}	—	—	80
Reverse Transfer Capacitance		C_{RSS}	—	—	25
SWITCHING CHARACTERISTICS					
Turn-On Delay Time	$(V_{DS} = 0.5 V_{(BR)DSS},$ $I_D = 0.3 \text{ A}, Z_0 = 50 \Omega)$	$t_{d(on)}$	—	—	15
Rise Time		t_r	---	—	25
Turn-Off Delay Time		$t_{d(off)}$	—	—	15
Fall Time		t_f	—	—	15
SOURCE-DRAIN DIODE CHARACTERISTICS					
Diode Forward Voltage ($V_{GS} = 0$)	$I_S = 0.6 \text{ A}$, IRFD210 $I_S = 0.45 \text{ A}$, IRFD213	V_F	—	—	2.0 1.8
Continuous Source Current, Body Diode	IRFD210 IRFD213	I_S	—	—	0.6 0.45
Pulsed Source Current, Body Diode	IRFD210 IRFD213	I_{SM}	—	—	2.5 1.8
Forward Turn-On Time	$(I_S = \text{Rated } I_S, V_{GS} = 0)$	t_{on}	negligible		
Reverse Recovery Time		t_{rr}	—	290	---

 1 Pulse Test: Pulse Width $\leq 300 \mu\text{s}$, Duty Cycle $\leq 2.0\%$